

Technical Data Sheet

Moulded Epoxy Resin - Deep Pour

Feature

Moulded epoxy resin can be cured under room temperature, has 2:1 volume ratio, is very easy to operate, featuring a low viscosity and good flowing property, natural defoaming, anti-yellowing, high transparency, no rippling and bright in surface.

Properties before hardening

Part	Resin	Hardener
Colour	Transparent	Transparent
Specific gravity	1.15	0.97
Viscosity (25°C)	350-400CPS	50 MAXCPS
Mixing ratio	A: B = 100:50(volume ratio)	
Hardening conditions	25 °C×72H (100g)	
Usable time	25°C×300min (100g)	

Properties after hardening

Hardness, shore	D <75
Withstand voltage, KV/mm	22
Flexural strength, Kg/mm ²	28
Volume resistivity, Ohm ³	1x10 ¹⁵
Surface resistance, Ohm ²	5x10 ¹⁵
Thermal conductivity, W/M.K	1.36
Induced electric loss, 1KHZ	0.42
Withstand high temperature,	90°C
Moisture absorption, %	<0.15
Compressive strength, Kg/ mm ²	8.4

Notice: The above data is typical data measured by the laboratory environment under the temperature of 25 °C, and humidity of 70%. For customers' reference only.